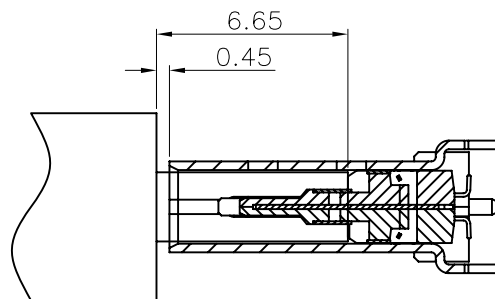
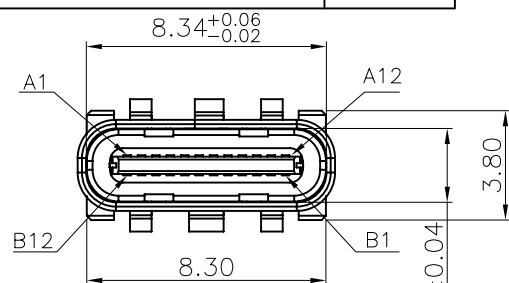
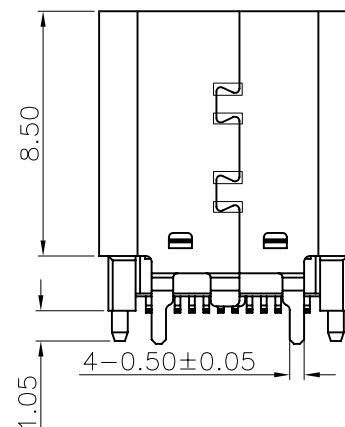
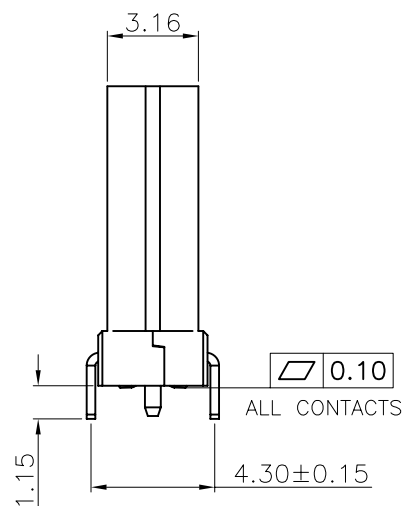
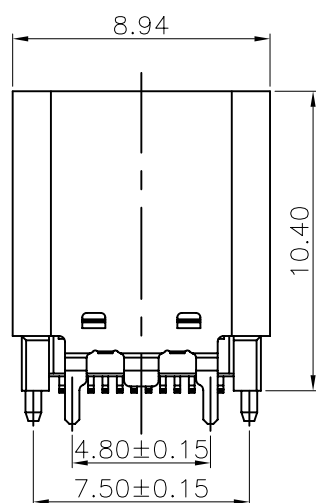


REV	ECN No.	DATE	REMARK
A0	NEW	2019.11.21	NEW RELEASE

TYPE C协会认证TID NO. 3733



AFTER MATING



NOTE:

1. MATERIAL SPECIFICATION:
1. HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC (LCP), UL94 V-0.
2. CONTACTS: COPPER ALLOY (C1814) T=0.12mm
3. MID PLATE: STAINLESS STEEL (SUS301) T=0.20mm
4. EMI PLATE: STAINLESS STEEL (SUS301) T=0.10mm
5. SHELL: STAINLESS STEEL (SUS304) T=0.30mm
2. PLATING SPECIFICATION:
2-1. CONTACTS:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
- 2-2. FRONT SHELL & OUTER SHELL:
Ni 30u" MIN. UNDER PLATED OVER ALL.
- 2-3. MID PLATE:
CLEAR ONLY
- 2-4. EMI PLATE:
CLEAR ONLY
3. MECHANICAL PERFORMANCE,
3-1. INSERTION FORCE: 0.5~2.0kgf.
3-2. EXTRACTION FORCE: 0.8kgf~2.0kgf.
3-3. DURABILITY: 10000 CYCLES.
4. ELECTRICAL PERFORMANCE,
4-1. CURRENT RATING: 5.0A
VOLTAGE RATING: 5.0V
4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
4-3. INSULATION RESISTANCE: 100MΩ MIN
4-4. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25°C~+85°C.
6. IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

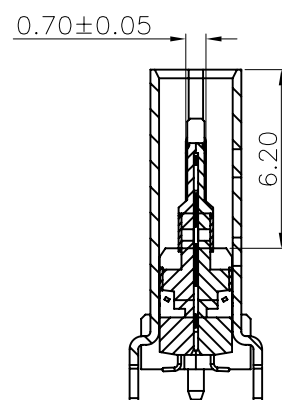
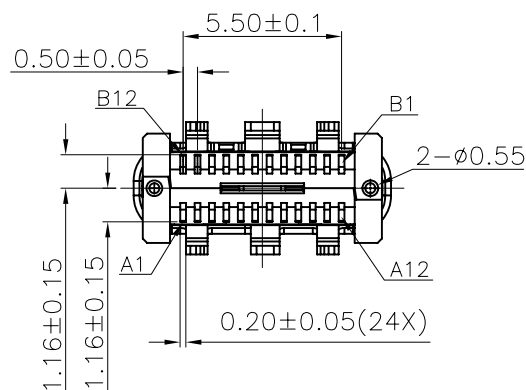
7. PART NUMBER CODE:

C F175 - 24 S L B XX R - C3

$\overline{\textcircled{1}}$

$\overline{\textcircled{2}}$

- ① HOUSING: B:BLACK ② CONTACTS PLATED: 02:半金锡3u"



SECTION:A-A

PART NO.:		 深圳市中兴科兴达科技有限公司 SHENZHEN ZDT TECHNOLOGY CO., LTD		DRAWN BY		DATE	
SEE THE PART NUMBER CODE				SAM		2019.11.21	
QUALITY SYMBOL 0 ▽=0							

frame size: A4

F



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C

A

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